Laird TECHNOLOGIES

Innovative **Technology** for a **Connected** World

Tflex™ 300 Series
Thermal Gap Filler



UNIQUE SILICONE GEL OFFERS COMPLIANCY, THERMAL RESISTANCE

Tflex™ 300, at pressures of 50psi, will deflect to over 50% the original thickness. This high rate of compliancy allows the material to "totally blanket" the component, enhancing thermal transfer. The material has a very low compression set enabling the pad to be reused many times.

Tflex™ 300, in achieving its stellar compliancy, does not sacrifice thermal performance. With a thermal conductivity of 1.2 W/mK, low thermal resistances can be achieved at low pressures.

Tflex™ 300-H is offered with a hard, metallized liner option for easy handling and improved rework. The metallized liner's lower coefficient of friction also allows for easy assembly of parts that must slide together, such as a card into a chassis.

FEATURES AND BENEFITS

- Extreme compliancy allows material to "totally blanket" component(s)
- Thermal conductivity of 1.2 W/mK
- Available in thicknesses from 0.020" - 0.200" (.5mm – 5.0mm)
- Low compression set enables the pad to be reused many times

APPLICATIONS

- Notebook and desktop computers
- Telecommunication hardware
- Flat panel displays
- Memory modules
- Power conversion equipment
- Set top box
- Lighting ballast
- Automotive electronics
- LED lighting
- Handheld electronics
- Optical disk drives
- Vibration dampening

global solutions: local support™

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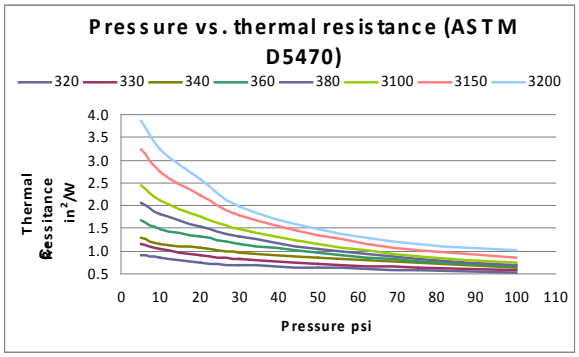
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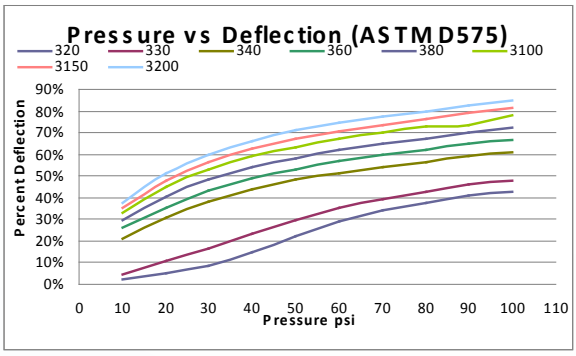
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Thermal Gap Filler

TFLEX™ 300 TYPICAL PROPERTIES

	TFLEX™ 300	TEST METHOD
Construction	Filled silicone elastomer	NA
Color	Light green	Visual
Thermal Conductivity	1.2 W/mK	ASTM D5470
Hardness (Shore 00)	40 (at 3 second delay)	ASTM D2240
Density	1.78 g/cc	Helium Pyncometer
Thickness Range	0.020" - .200" (0.5 - 5.0mm)*	
Thickness Tolerance	±10%	
UL Flammability Rating	94 V0	UL
Temperature Range	-40°C to 160°C	NA
Volume Resistivity	10 ^13 ohm-cm	ASTM D257
Outgassing TML	0.56%	ASTM E595
Outgassing CVCM	0.10%	ASTM E595
Coefficient Thermal Expansion (CTE)	600 ppm/C	IPC-TM-650 2.4.24





STANDARD THICKNESSES

0.020 to 0.200-inch (0.5 to 5.0mm)*
0.020 to 0.200-inch thick material available in 0.010-inch (0.25mm) increments
*Inquire about availability of material and options above 0.200-inches
** FG (fiberglass) is standard for thicknesses 0.020" (0.50mm) and 0.030" (0.76mm)

OPTIONS

PET dielectric "H" liner available for applications where easy slide assembly is desirable

MATERIAL NAME AND THICKNESS

Tflex™ indicates elastomeric gap filler product line
3xxx indicates high recovery '3 series' 1.2 W/mK material
-DC1 designates proprietary tack eliminated coating
-H indicates hard PET liner option

EXAMPLES

Tflex™ 3120 = standard 0.120-inch thick Tflex™ 300 material
Tflex™ 3120DC1 = 0.120-inch thick material with DC1 coating
Tflex™ 3120H = 0.120-inch thick material with hard PET liner

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В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

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